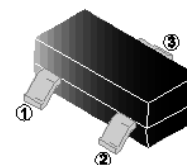


RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

- High Conductance
- Low Current Leakage
- Small Outline Surface Mount Package

SOT-323



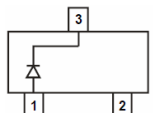
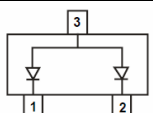
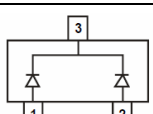
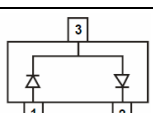
MECHANICAL DATA

- Case: SOT-323, Molded Plastic
- Terminals: solderable per MIL-STD-202, Method 208
- Lead (Pb)-free and Halogen-free

PACKAGE INFORMATION

Package	MPQ	Leader Size
SOT-323	3K	7 inch

ORDER INFORMATION

Part Number	Equivalent Circuit	Marking
BAS70W-C		73 / K73 / BE
BAS70W-04-C		74 / K74
BAS70W-05-C		75 / K75
BAS70W-06-C		76 / K76

ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise specified)

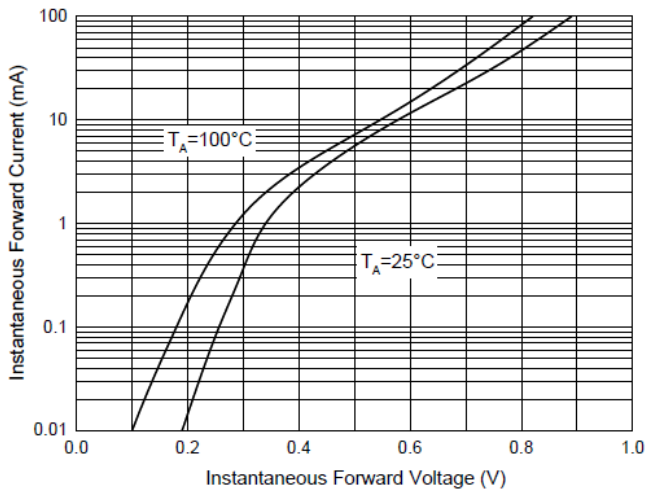
Parameter	Symbol	Ratings	Unit
Reverse Voltage	V _R	70	V
Forward Continuous Current	I _F	70	mA
Power Dissipation	P _D	200	mW
Non-Repetitive Peak Forward Surge Current @t=1s	I _{FSM}	100	mA
Thermal Resistance from Junction-Ambient	R _{θJA}	430	°C/W
Soldering Temperature During	T _L	260	°C
Junction & Storage Temperature	T _J , T _{STG}	125, -55~150	

ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

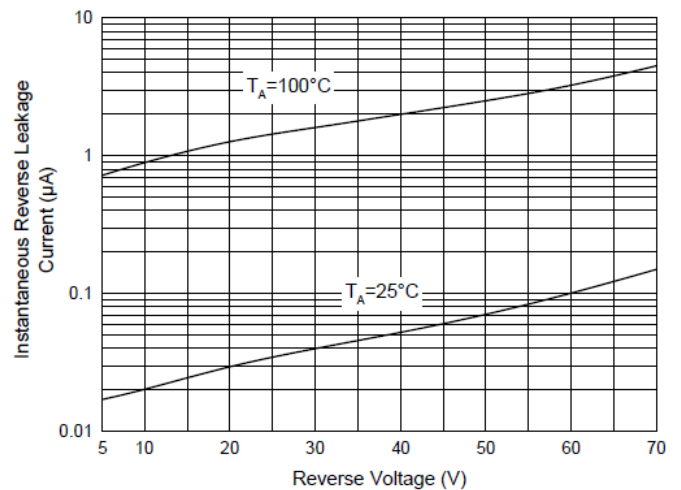
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward Voltage	V_F	-	-	0.41	V	$I_F=1\text{mA}$
		-	-	1		$I_F=15\text{mA}$
Reverse Breakdown Voltage	V_R	70	-	-		$I_R=10\mu\text{A}$
Reverse Current	I_R	-	-	100	nA	$V_R=50\text{V}$
Junction Capacitance	C_J	-	2	-	pF	$V_R=0\text{V}$, $f=1\text{MHz}$
Reverse Recovery Time	T_{rr}	-	5	-	nS	$I_F=I_R=10\text{mA}$, $I_R=1\text{mA}$

RATINGS AND CHARACTERISTIC CURVES

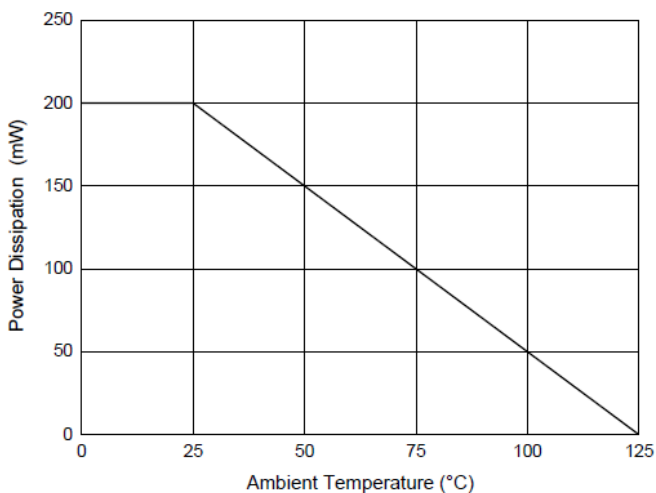
Typical Instantaneous Forward Characteristics



Typical Reverse Leakage Characteristics

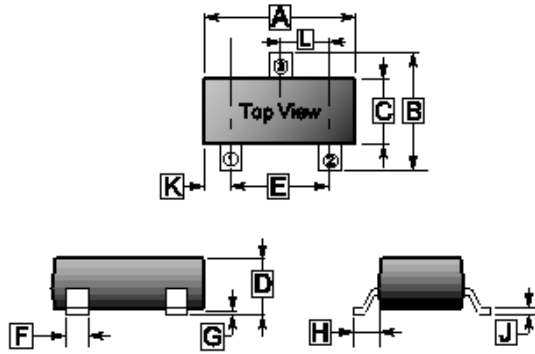


Power Derating Curve



PACKAGE OUTLINE DIMENSIONS

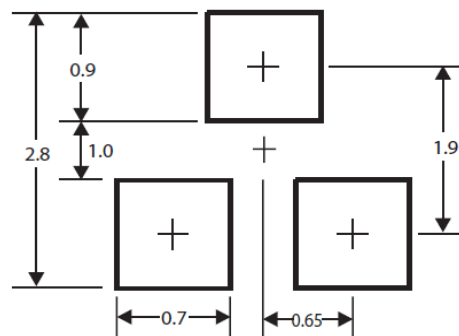
SOT-323



REF.	Millimeter	
	Min.	Max.
A	1.80	2.20
B	1.80	2.55
C	1.10	1.40
D	0.80	1.15
E	1.20	2.00
F	0.15	0.50
G	0.10 REF.	
H	0.525 REF.	
J	0.05	0.25
K	0.35 REF.	
L	0.65 TYP.	

MOUNTING PAD LAYOUT

SOT-323



*Dimensions in millimeters